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BAP55LX

Silicon PIN diode

Rev. 4 — 6 August 2013

Product data sheet

1. Product profile

1.1 General description

Planar PIN diode in a SOD882D leadless ultra small plastic SMD package.

1.2 Features and benefits

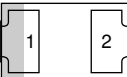

- High speed switching for RF signals
- Low diode capacitance
- Low forward resistance
- Very low series inductance
- For applications up to 3 GHz

1.3 Applications

- RF attenuators and switches

2. Pinning information

Table 1. Discrete pinning

Pin	Description	Simplified outline	Symbol
1	cathode [1]		
2	anode		

Transparent top view

sym006

[1] The marking bar indicates the cathode.

3. Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
BAP55LX	DFN1006D-2	leadless ultra small plastic package; 2 terminals; body 1 × 0.6 × 0.4 mm	SOD882D



4. Marking

Table 3. Marking codes

Type number	Marking code ^[1]
BAP55LX	1111 1101

[1] For SOD882D binary marking code description, see [Figure 1](#).

4.1 Binary marking code description

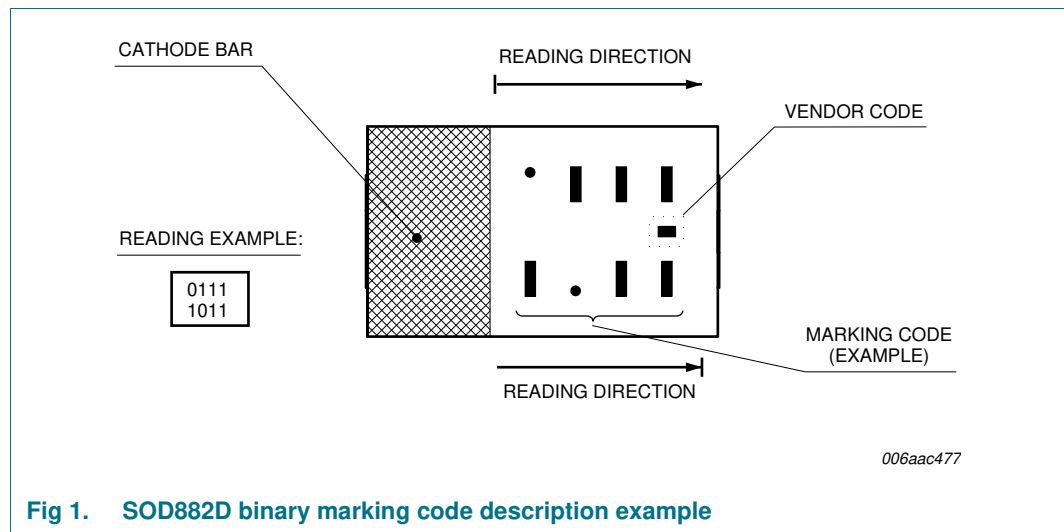


Fig 1. SOD882D binary marking code description example

5. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_R	reverse voltage		-	50	V
I_F	forward current		-	100	mA
P_{tot}	total power dissipation	$T_{sp} = 90\text{ °C}$	-	135	mW
T_{stg}	storage temperature		-65	+150	°C
T_j	junction temperature		-65	+150	°C

6. Thermal characteristics

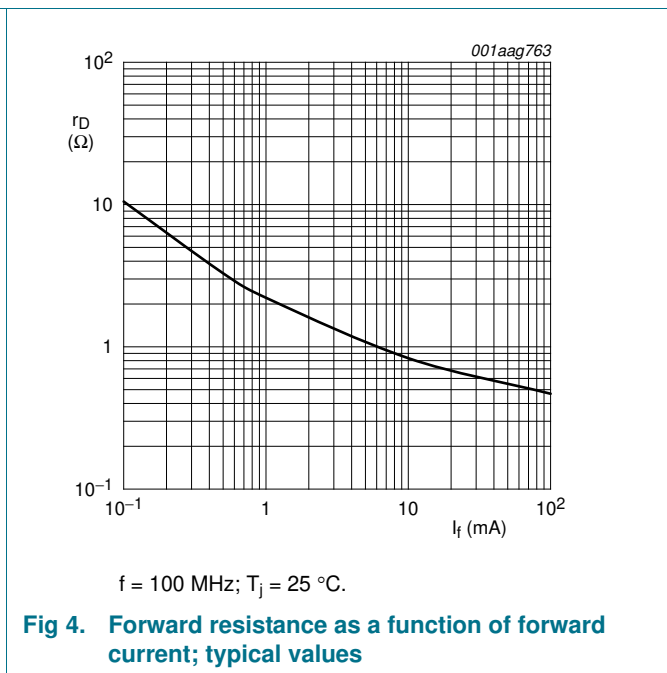
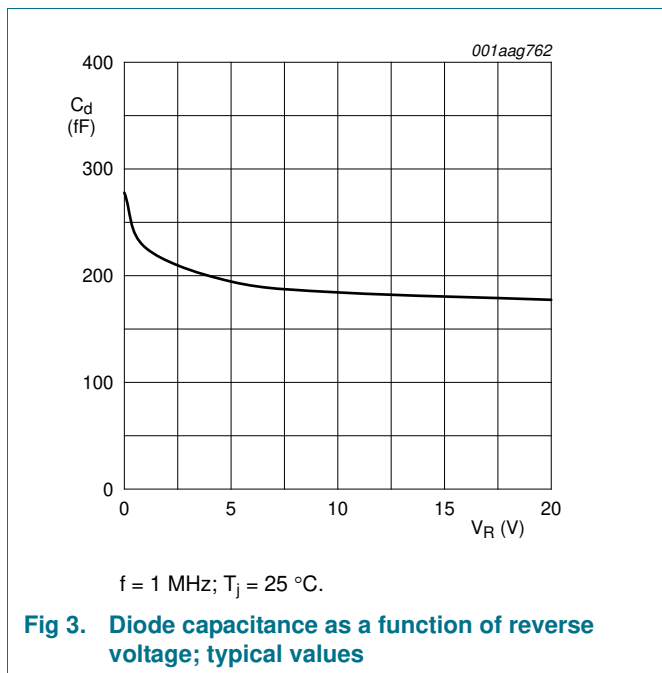
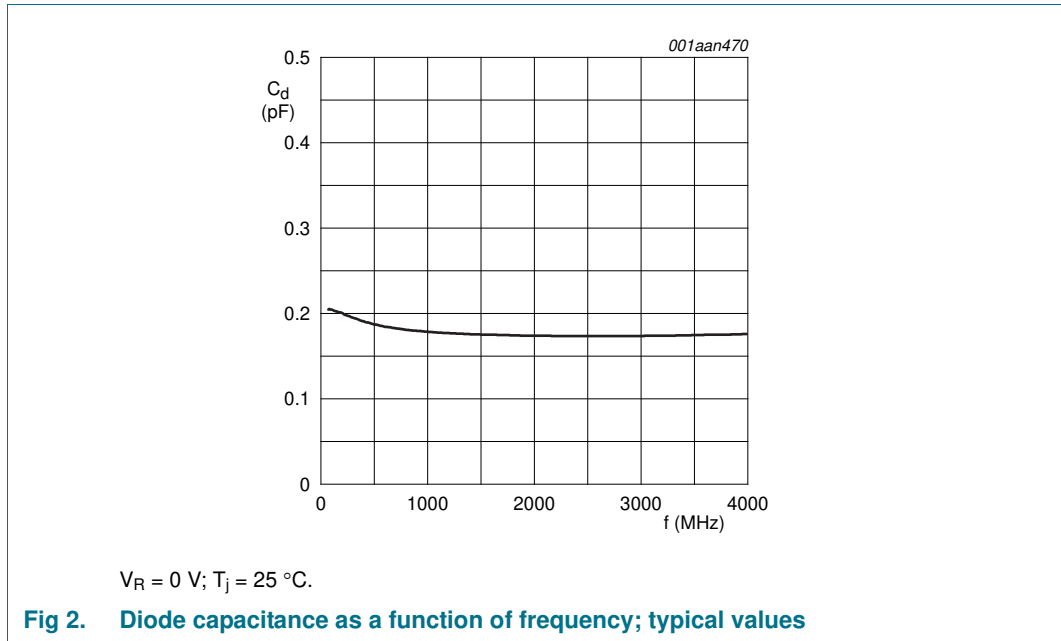
Table 5. Thermal characteristics

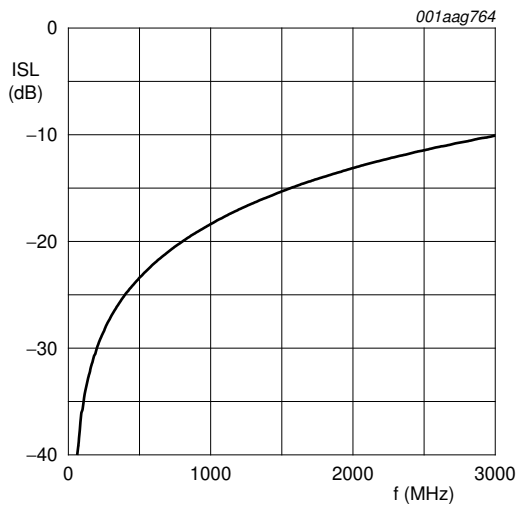
Symbol	Parameter	Conditions	Typ	Unit
$R_{th(j-sp)}$	thermal resistance from junction to solder point		78	K/W

7. Characteristics

Table 6. Characteristics
T_{amb} = 25 °C unless otherwise specified.

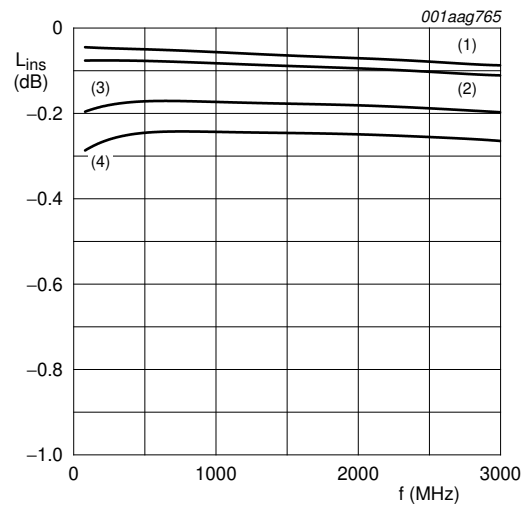
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _F	forward voltage	I _F = 50 mA	-	0.95	1.1	V
I _R	reverse current	V _R = 20 V	-	-	10	nA
		V _R = 50 V	-	-	100	nA
C _d	diode capacitance	see Figure 3 ; f = 1 MHz;				
		V _R = 0 V	-	0.28	-	pF
		V _R = 1 V	-	0.23	-	pF
		V _R = 20 V	-	0.18	0.28	pF
r _D	diode forward resistance	see Figure 4 ; f = 100 MHz;				
		I _F = 0.5 mA	-	3.3	4.5	Ω
		I _F = 1 mA	-	2.2	3.3	Ω
		I _F = 10 mA	-	0.8	1.2	Ω
		I _F = 100 mA	-	0.5	0.8	Ω
ISL	isolation	see Figure 5 ; V _R = 0 V;				
		f = 900 MHz	-	19	-	dB
		f = 1800 MHz	-	14	-	dB
		f = 2450 MHz	-	12	-	dB
L _{ins}	insertion loss	see Figure 6 ; I _F = 0.5 mA;				
		f = 900 MHz	-	0.24	-	dB
		f = 1800 MHz	-	0.25	-	dB
		f = 2450 MHz	-	0.26	-	dB
L _{ins}	insertion loss	see Figure 6 ; I _F = 1 mA;				
		f = 900 MHz	-	0.17	-	dB
		f = 1800 MHz	-	0.18	-	dB
		f = 2450 MHz	-	0.19	-	dB
L _{ins}	insertion loss	see Figure 6 ; I _F = 10 mA;				
		f = 900 MHz	-	0.08	-	dB
		f = 1800 MHz	-	0.09	-	dB
		f = 2450 MHz	-	0.10	-	dB
L _{ins}	insertion loss	see Figure 6 ; I _F = 100 mA;				
		f = 900 MHz	-	0.05	-	dB
		f = 1800 MHz	-	0.07	-	dB
		f = 2450 MHz	-	0.08	-	dB
τ _L	charge carrier life time	when switched from I _F = 10 mA to I _R = 6 mA; R _L = 100 Ω; measured at I _R = 3 mA	0.225	0.27	-	μs
L _S	series inductance	I _F = 100 mA; f = 100 MHz	-	0.4	-	nH





$T_{amb} = 25\text{ }^{\circ}\text{C}$
 Diode zero biased and inserted in series with a 50 Ω stripline circuit

Fig 5. Isolation of the diode as a function of frequency; typical values

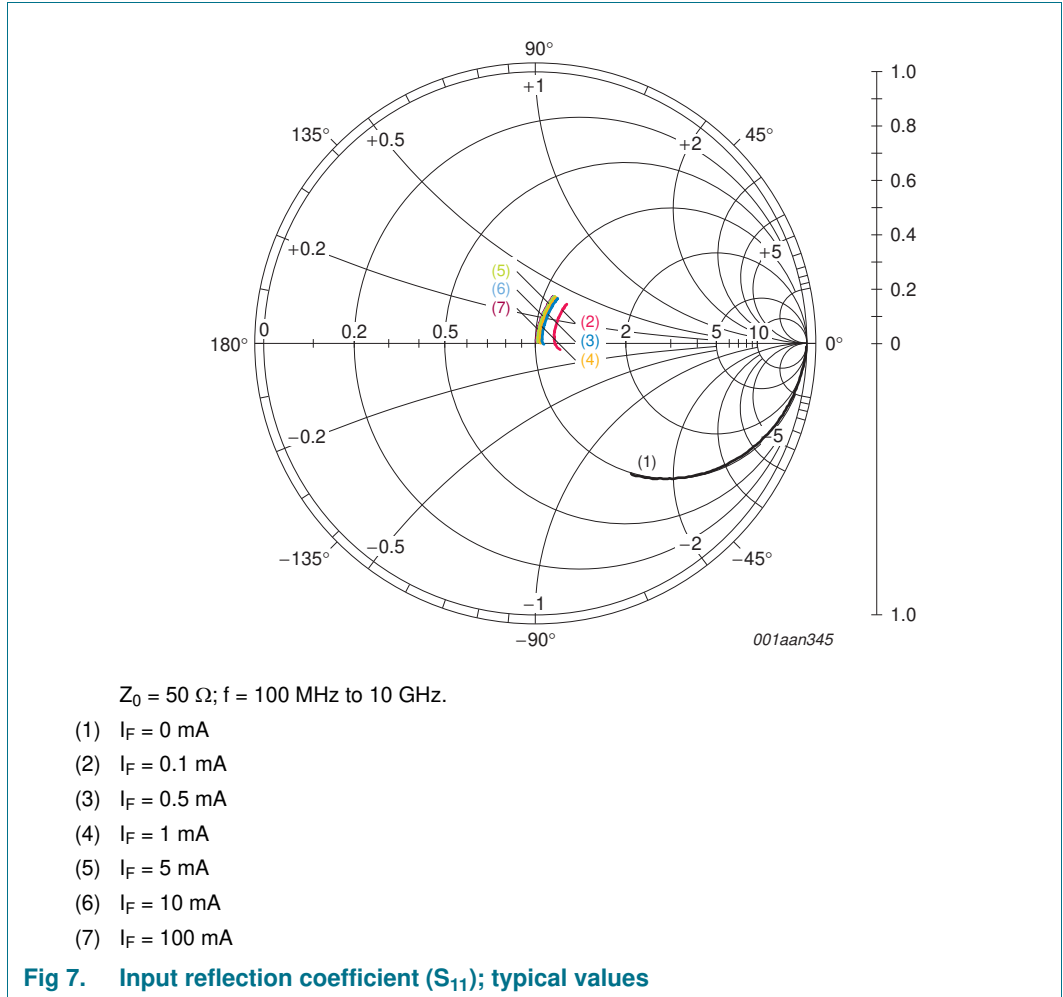


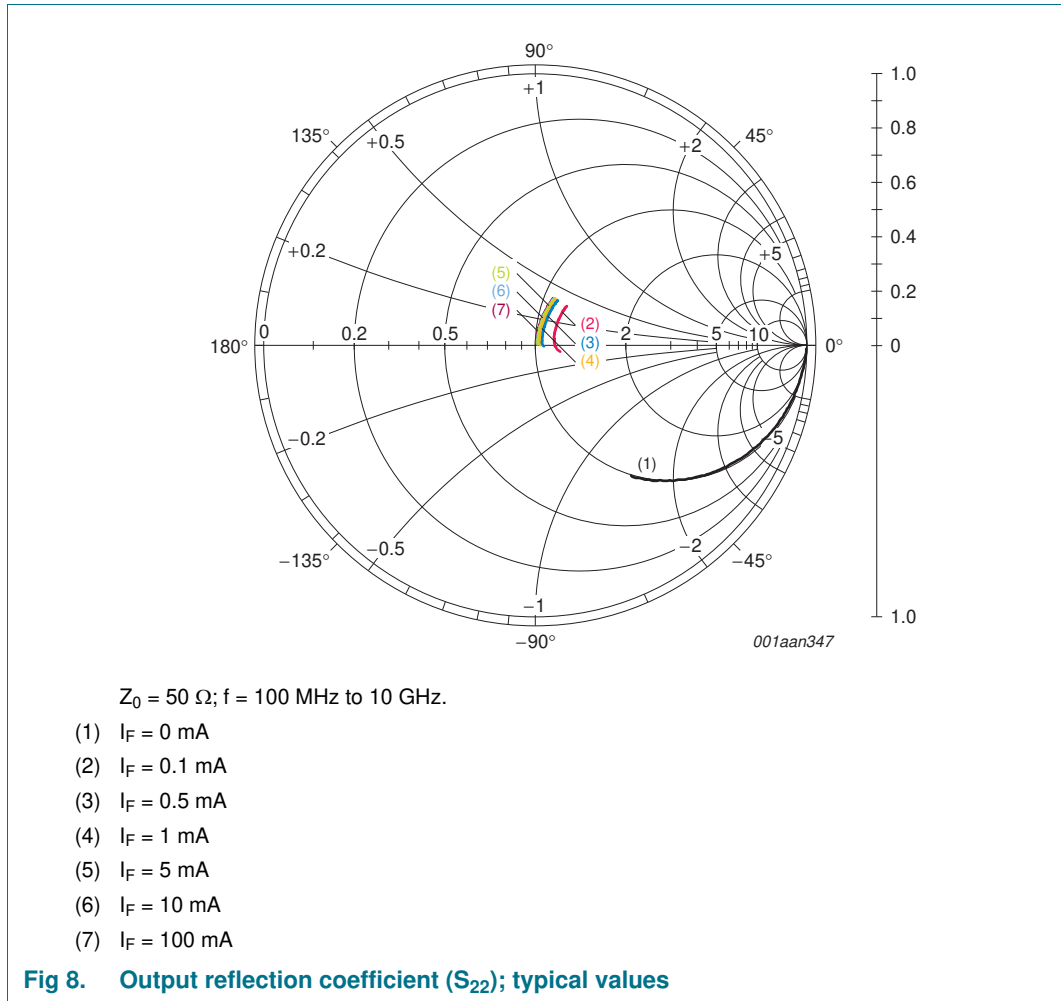
$T_{amb} = 25\text{ }^{\circ}\text{C}$
 (1) $I_F = 100\text{ mA}$
 (2) $I_F = 10\text{ mA}$
 (3) $I_F = 1\text{ mA}$
 (4) $I_F = 0.5\text{ mA}$
 Diode inserted in series with a 50 Ω stripline circuit and biased via the analyzer Tee network

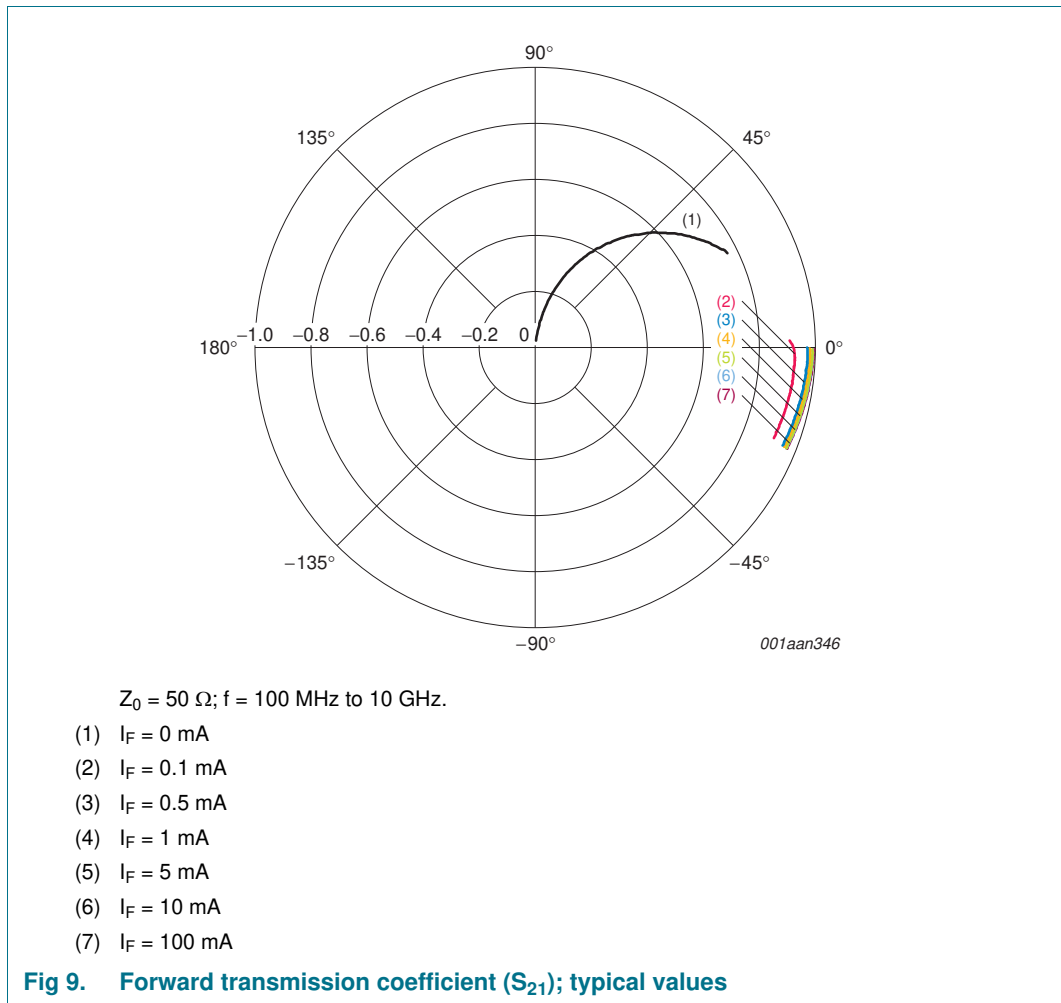
Fig 6. Insertion loss of the diode as a function of frequency; typical values

7.1 S-parameters

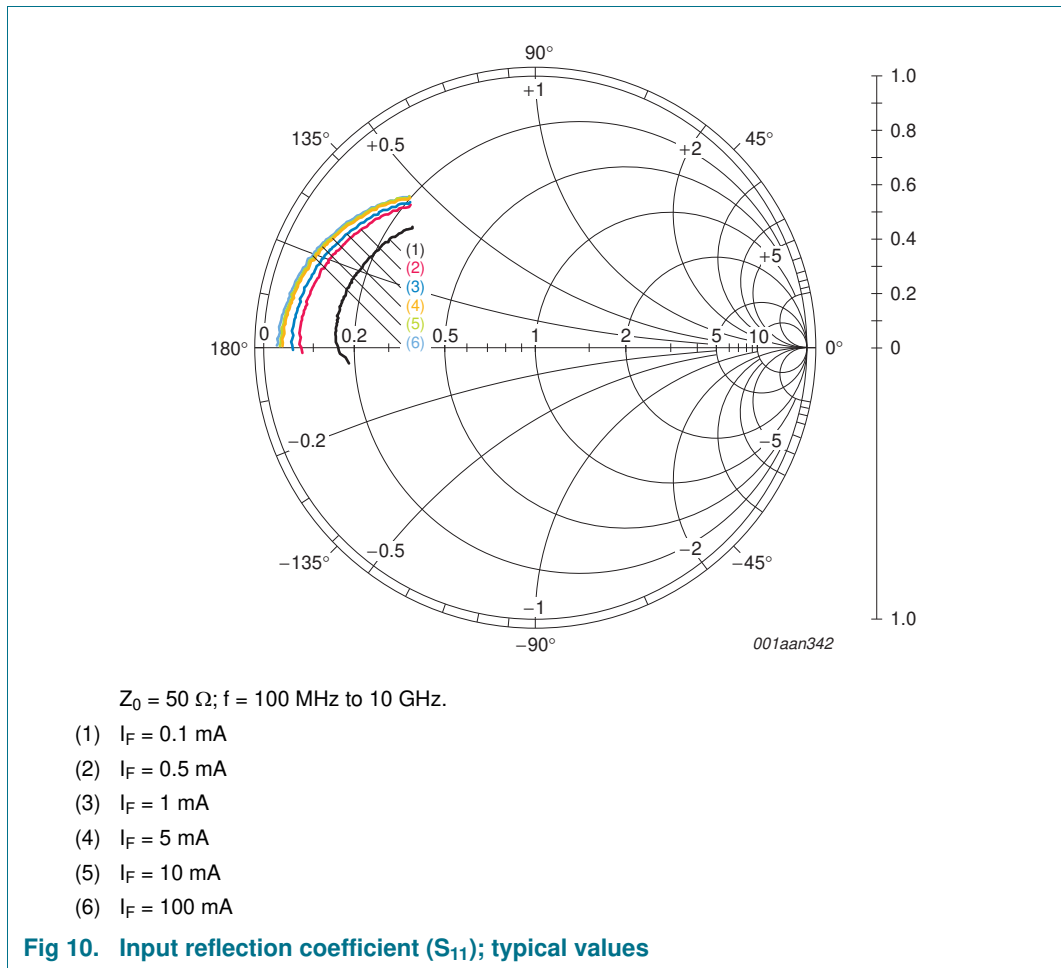
7.1.1 Diode in series configuration

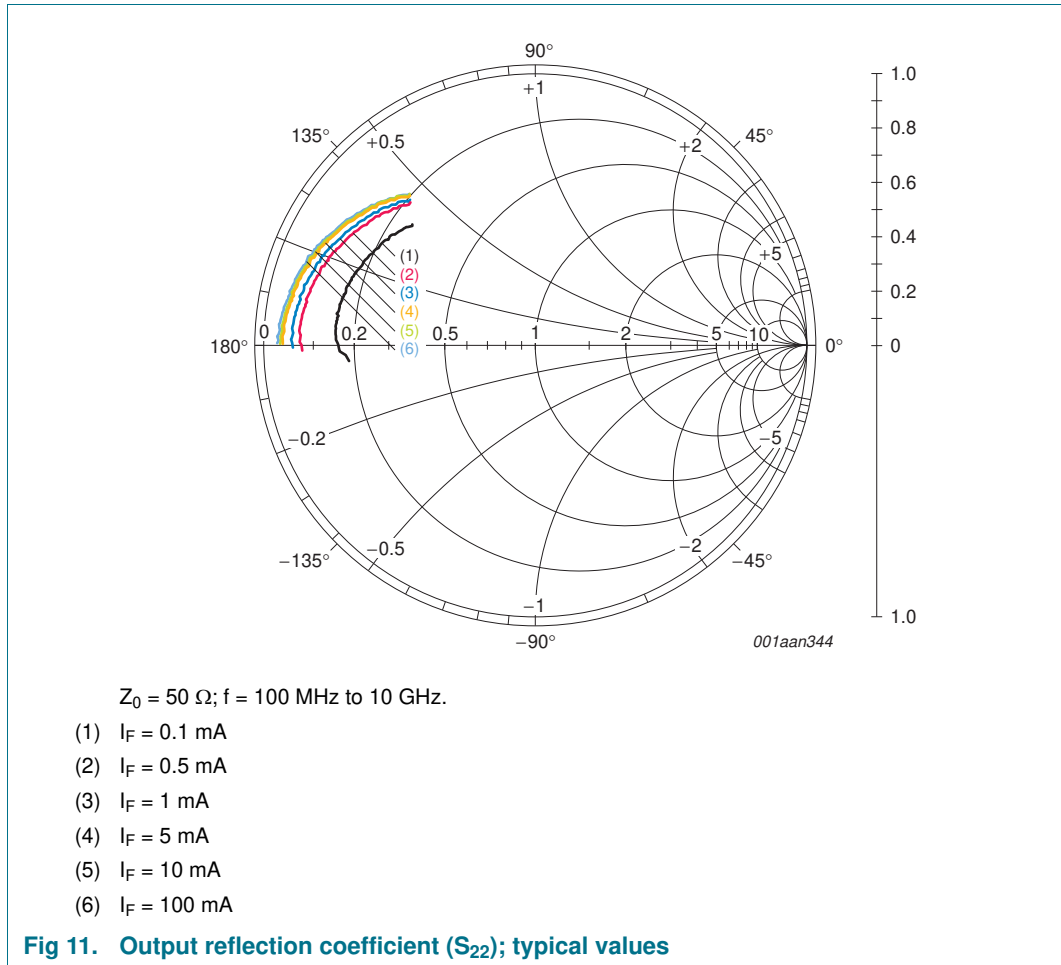


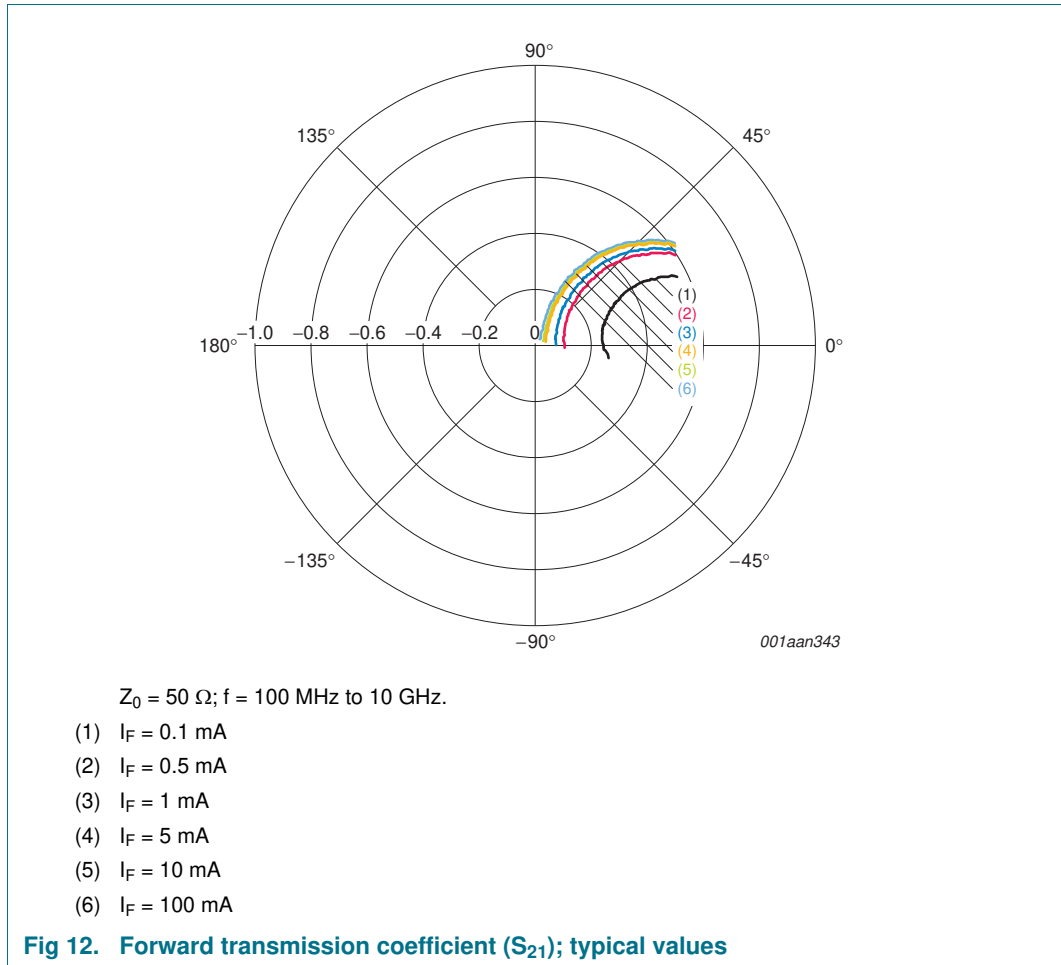




7.1.2 Diode in parallel configuration







8. Package outline

DFN1006D-2: Leadless ultra small plastic package; 2 terminals; body 1 x 0.6 x 0.4 mm

SOD882D

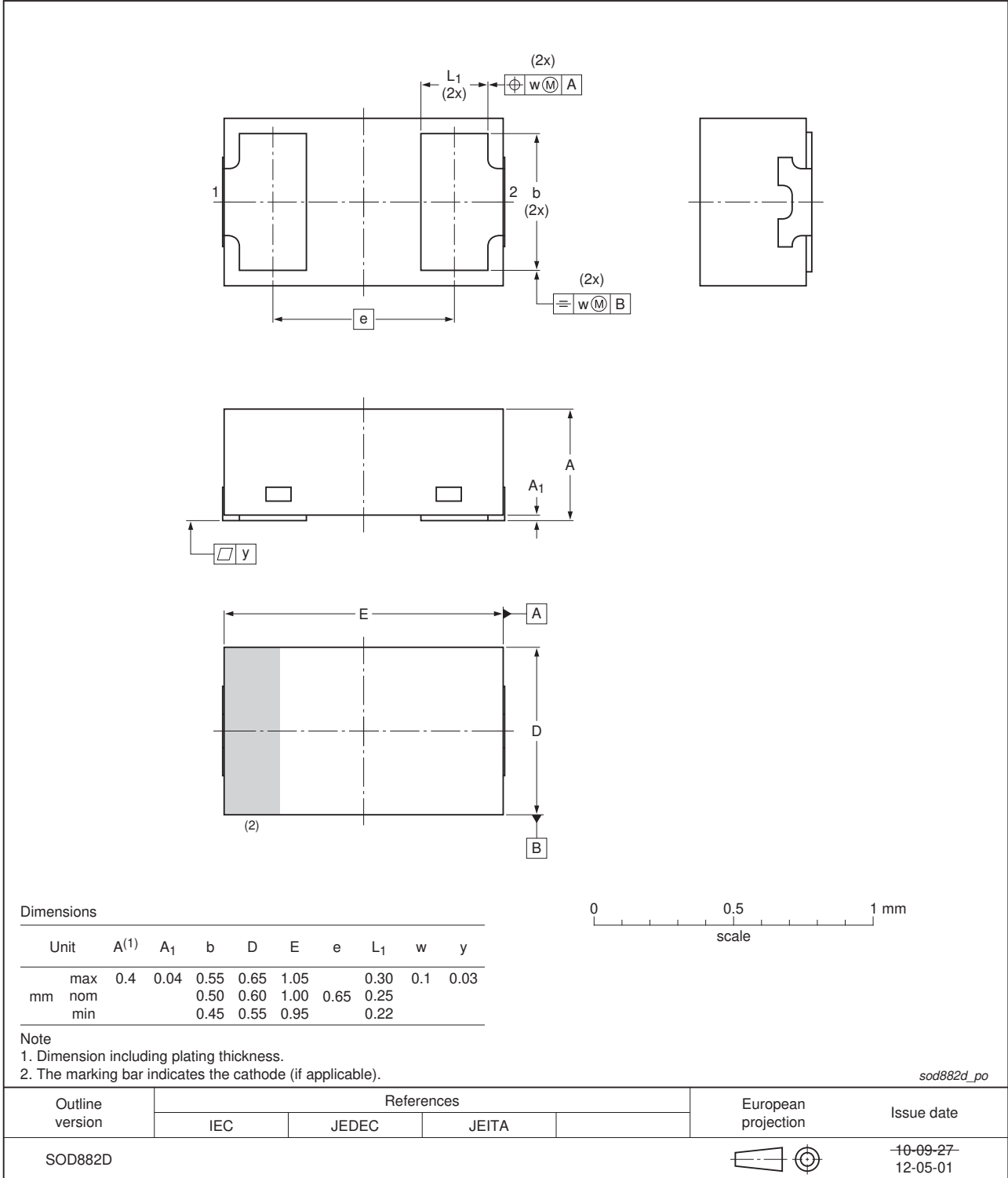


Fig 13. Package outline SOD882D (DFN1006D-2)

9. Abbreviations

Table 7. Abbreviations

Acronym	Description
PIN	P-type, Intrinsic, N-type
SMD	Surface Mounted Device
RF	Radio Frequency

10. Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAP55LX v.4	20130806	Product data sheet	-	BAP55LX v.3
Modifications:	<ul style="list-style-type: none"> • Section 1.1 on page 1: Changed package to SOD882D • Table 1 on page 1: Changed simplified outline to SOD882D • Table 2 on page 1: Changed package to SOD882D • Section 4 on page 2: Update 'Marking' section • Section 8 on page 12: Changed package to SOD882D 			
BAP55LX v.3	20110113	Product data sheet	-	BAP55LX v.2
BAP55LX v.2	20101216	Product data sheet	-	BAP55LX v.1
BAP55LX v.1	20070730	Product data sheet	-	-

11. Legal information

11.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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